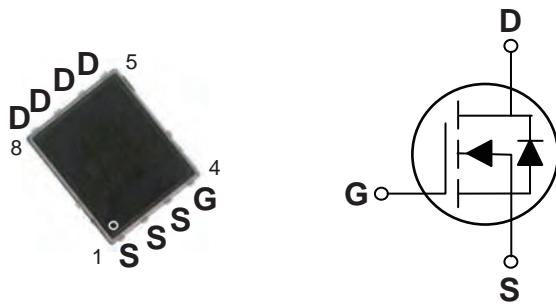


## 150V N-Channel MOSFETs

### General Description

These N-Channel enhancement mode power field effect transistors are using trench DMOS technology. This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and withstand high energy pulse in the avalanche and commutation mode. These devices are well suited for high efficiency fast switching applications.

### PPAK5X6 Pin Configuration



BVDSS	RDS(ON)	ID
150V	65mΩ	15A

### Features

- 150V, 15A, RDS(ON) = 65mΩ @ VGS = 10V
- VGS Guarantee  $\pm 25V$
- Improved dv/dt capability
- Fast switching
- Green Device Available

### Applications

- Motor Drive
- Power Tools
- LED Lighting

### Absolute Maximum Ratings (T<sub>C</sub>=25°C unless otherwise noted)

Symbol	Parameter	Rating	Units
V <sub>DS</sub>	Drain-Source Voltage	150	V
V <sub>GS</sub>	Gate-Source Voltage	$\pm 25$	V
I <sub>D</sub>	Drain Current – Continuous (T <sub>C</sub> =25°C)	15	A
	Drain Current – Continuous (T <sub>C</sub> =100°C)	9.5	A
I <sub>DM</sub>	Drain Current – Pulsed <sup>d</sup>	60	A
P <sub>D</sub>	Power Dissipation (T <sub>C</sub> =25°C)	135	W
	Power Dissipation – Derate above 25°C	1.08	W/°C
T <sub>STG</sub>	Storage Temperature Range	-55 to 150	°C
T <sub>J</sub>	Operating Junction Temperature Range	-55 to 150	°C

### Thermal Characteristics

Symbol	Parameter	Typ.	Max.	Unit
R <sub>θJA</sub>	Thermal Resistance Junction to ambient	---	62	°C/W
R <sub>θJC</sub>	Thermal Resistance Junction to Case	---	0.92	°C/W



# FTK30N15DFN56

Electrical Characteristics ( $T_J=25^\circ\text{C}$ , unless otherwise noted)

## Off Characteristics

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
$\text{BV}_{\text{DSS}}$	Drain-Source Breakdown Voltage	$V_{\text{GS}}=0\text{V}$ , $I_D=250\mu\text{A}$	150	---	---	V
$\Delta \text{BV}_{\text{DSS}}/\Delta T_J$	$\text{BV}_{\text{DSS}}$ Temperature Coefficient	Reference to $25^\circ\text{C}$ , $I_D=1\text{mA}$	---	0.08	---	$\text{V}/^\circ\text{C}$
$I_{\text{DSS}}$	Drain-Source Leakage Current	$V_{\text{DS}}=120\text{V}$ , $V_{\text{GS}}=0\text{V}$ , $T_J=25^\circ\text{C}$	---	---	1	$\mu\text{A}$
		$V_{\text{DS}}=96\text{V}$ , $V_{\text{GS}}=0\text{V}$ , $T_J=125^\circ\text{C}$	---	---	30	$\mu\text{A}$
$I_{\text{GSS}}$	Gate-Source Leakage Current	$V_{\text{GS}}=\pm 25\text{V}$ , $V_{\text{DS}}=0\text{V}$	---	---	$\pm 100$	nA

## On Characteristics

$R_{\text{DS(ON)}}$	Static Drain-Source On-Resistance <sup>3</sup>	$V_{\text{GS}}=10\text{V}$ , $I_D=6\text{A}$	---	52	65	$\text{m}\Omega$
		$V_{\text{GS}}=6\text{V}$ , $I_D=4\text{A}$	---	65	90	$\text{m}\Omega$
$V_{\text{GS(th)}}$	Gate Threshold Voltage	$V_{\text{GS}}=V_{\text{DS}}$ , $I_D = 250\mu\text{A}$	2	3	4	V
			---	-2.5	---	$\text{mV}/^\circ\text{C}$

## Dynamic and switching Characteristics

$Q_g$	Total Gate Charge <sup>2,3</sup>	$V_{\text{DS}}=30\text{V}$ , $V_{\text{GS}}=10\text{V}$ , $I_D=4\text{A}$	---	30	45	nC
$Q_{\text{gs}}$	Gate-Source Charge <sup>2,3</sup>		---	8.7	14	
$Q_{\text{gd}}$	Gate-Drain Charge <sup>2,3</sup>		---	8	15	
$T_{\text{d(on)}}$	Turn-On Delay Time <sup>2,3</sup>	$V_{\text{DD}}=30\text{V}$ , $V_{\text{GS}}=10\text{V}$ , $R_G=6\Omega$ $I_D=1\text{A}$	---	14.5	28	ns
$T_r$	Rise Time <sup>2,3</sup>		---	19.2	18	
$T_{\text{d(off)}}$	Turn-Off Delay Time <sup>2,3</sup>		---	33.6	60	
$T_f$	Fall Time <sup>2,3</sup>		---	22.8	25	
$C_{\text{iss}}$	Input Capacitance		---	1790	3000	pF
$C_{\text{oss}}$	Output Capacitance	$V_{\text{DS}}=30\text{V}$ , $V_{\text{GS}}=0\text{V}$ , $F=1\text{MHz}$	---	160	300	
$C_{\text{rss}}$	Reverse Transfer Capacitance		---	82	160	
$R_g$	Gate Resistance	$V_{\text{GS}}=0\text{V}$ , $V_{\text{DS}}=0\text{V}$ , $F=1\text{MHz}$	---	1.4	2.8	$\Omega$

## Drain-Source Diode Characteristics and Maximum Ratings

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
$I_s$	Continuous Source Current	$V_G=V_D=0\text{V}$ , Force Current	---	---	15	A
			---	---	30	A
$V_{\text{SD}}$	Diode Forward Voltage	$V_{\text{GS}}=0\text{V}$ , $I_s=1\text{A}$ , $T_J=25^\circ\text{C}$	---	---	1.2	V
			---	---	---	ns
$Q_{\text{rr}}$	Reverse Recovery Charge <sup>2</sup>	$V_{\text{GS}}=0\text{V}$ , $I_s=1\text{A}$ , $dI/dt=100\text{A}/\mu\text{s}$	---	---	---	nC

Note :

1. Repetitive Rating : Pulsed width limited by maximum junction temperature.
2. The data tested by pulsed , pulse width  $\leq 300\mu\text{s}$  , duty cycle  $\leq 2\%$ .
3. Essentially independent of operating temperature.

## ELECTRICAL CHARACTERISTICS CURVES

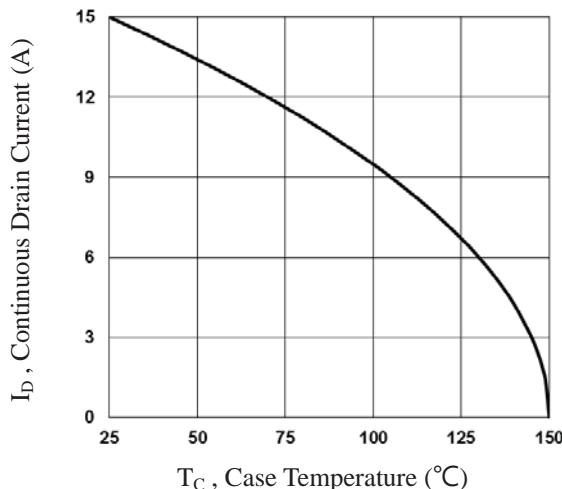


Fig.1 Continuous Drain Current vs.  $T_c$

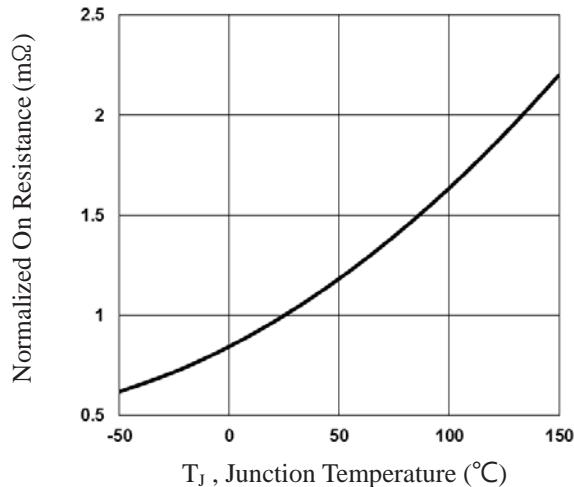


Fig.2 Normalized RDSON vs.  $T_j$

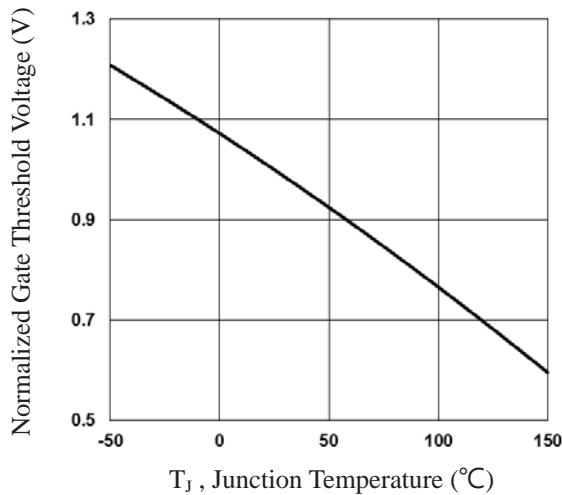


Fig.3 Normalized  $V_{th}$  vs.  $T_j$

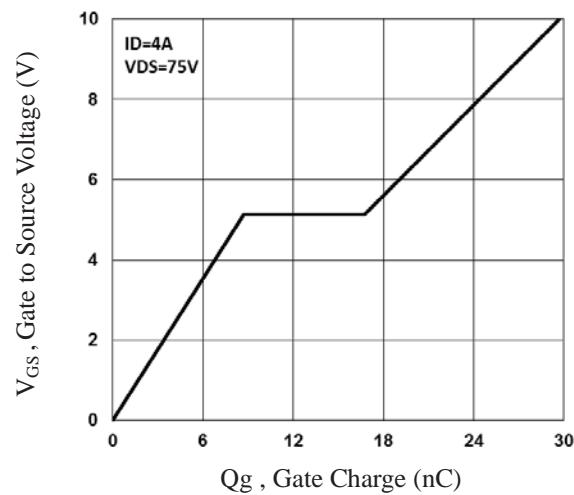


Fig.4 Gate Charge Characteristics

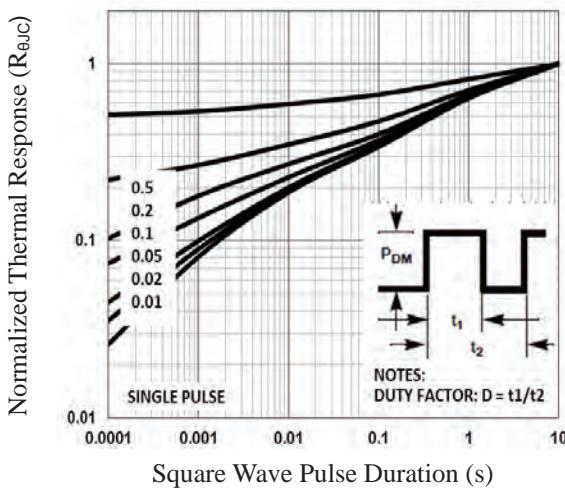


Fig.5 Normalized Transient Impedance

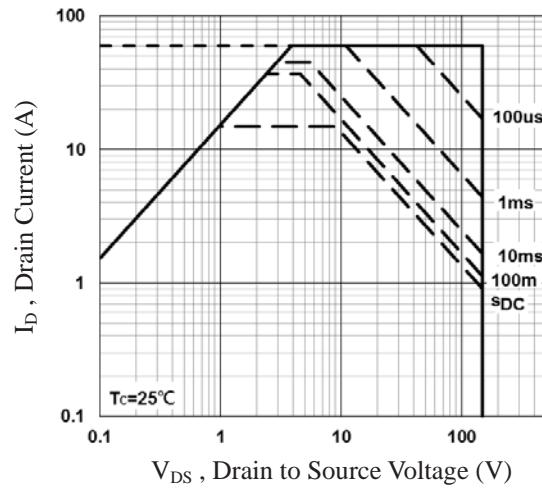


Fig.6 Maximum Safe Operation Area

## ELECTRICAL CHARACTERISTICS CURVES (Con.)

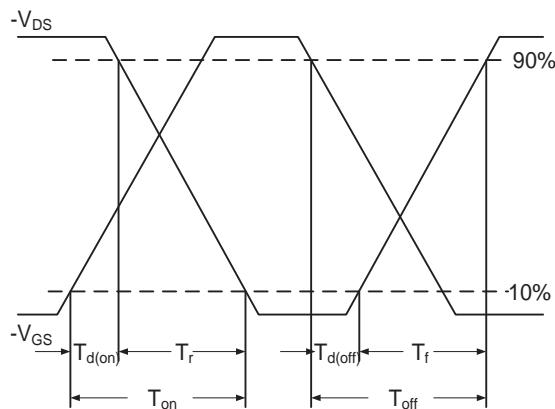


Fig.7 Switching Time Waveform

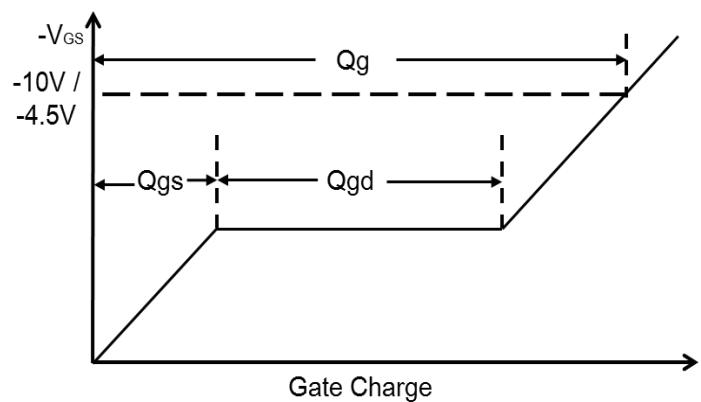
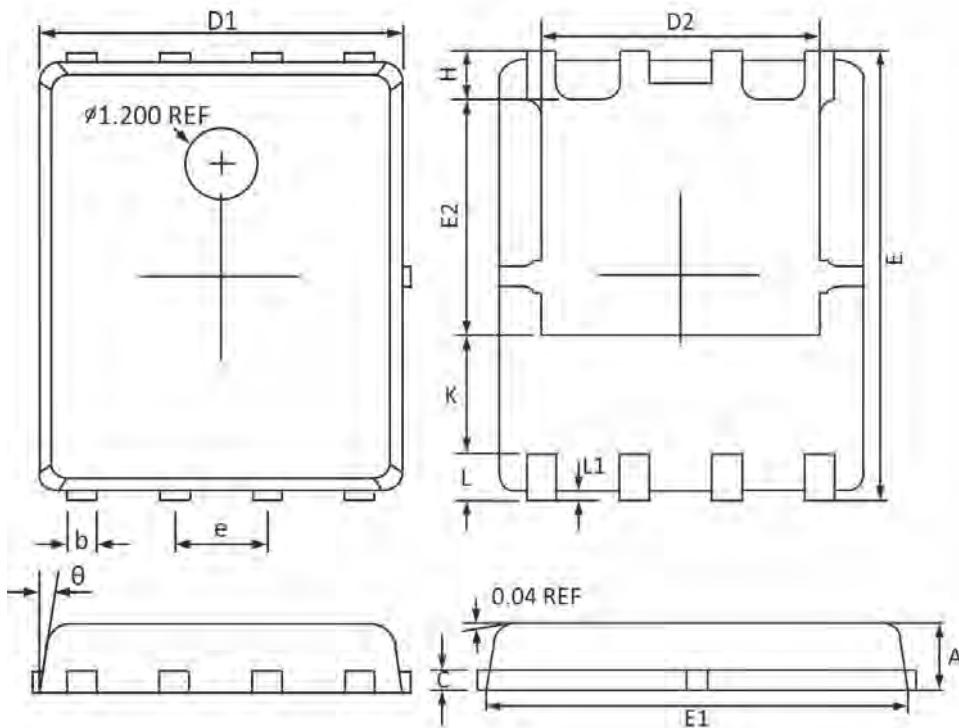


Fig.8 Gate Charge Waveform

## PPAK5x6 PACKAGE INFORMATION



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	MAX	MIN	MAX	MIN
A	1.100	0.800	0.043	0.031
b	0.510	0.330	0.020	0.013
C	0.300	0.200	0.012	0.008
D1	5.100	4.800	0.201	0.189
D2	4.100	3.610	0.161	0.142
E	6.200	5.900	0.244	0.232
E1	5.900	5.700	0.232	0.224
E2	3.780	3.350	0.149	0.132
e	1.27BSC		0.05BSC	
H	0.700	0.410	0.028	0.016
K	1.500	1.100	0.059	0.043
L	0.710	0.510	0.028	0.020
L1	0.200	0.060	0.008	0.002
θ	12°	0°	12°	0°